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(54) Title: DICING/DIE BONDING FILM AND METHOD OF MANUFACTURING THE SAME



(57) Abstract: A dicing/die bonding sheet is made by joining a base film (1) and a silicone based adhesive agent layer (3) through the medium of an undercoat layer (2). This all-in-one dicing/die bonding sheet exhibits superior long-term storage stability and prevents chip delamination during dicing.



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